

ABSTRACT OF THE DISCLOSURE

A semiconductor device provided with a first semiconductor chip having a first functional surface formed with a first functional element and a first rear surface, a second semiconductor chip having a second functional surface which is formed with a second functional element, the second functional surface having a region opposed to the first functional surface of the first semiconductor chip and a non-opposed region defined 10 outside the opposed region, a connection member electrically connecting the first functional element and the second functional element, an insulation film continuously covering the non-opposed region of the second semiconductor chip and the first rear surface of the first 15 semiconductor chip, a rewiring layer provided on a surface of the insulation film, a protective resin layer covering the rewiring layer, and an external connection terminal projecting from the rewiring layer through the protective resin layer.